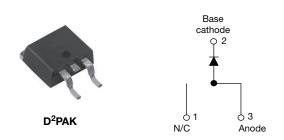
VS-10TQ035SPbF, VS-10TQ045SPbF

Vishay Semiconductors

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High Performance Schottky Rectifier, 10 A



PRODUCT SUMMARY					
Package	D ² PAK				
I _{F(AV)}	10 A				
V _R	35 V, 40 V, 45 V				
V _F at I _F	0.57 V				
I _{RM}	15 mA at 125 °C				
T _J max.	175 °C				
Diode variation	Single die				
E _{AS}	13 mJ				

FEATURES

- 175 °C T_J operation
- · Low forward voltage drop
- · High frequency operation
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance



- · Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 gualified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

DESCRIPTION

The VS-10TQ...SPbF Schottky rectifier series has been optimized for low reverse leakage at high temperature. The proprietary barrier technology allows for reliable operation up to 175 °C junction temperature. Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

MAJOR RATINGS AND CHARACTERISTICS					
SYMBOL	CHARACTERISTICS	VALUES	UNITS		
I _{F(AV)}	Rectangular waveform	10	A		
V _{RRM}		35/45	V		
I _{FSM}	t _p = 5 μs sine	1050	A		
V _F	10 A _{pk} , T _J = 125 °C	0.49	V		
TJ	Range	-55 to +175	°C		

VOLTAGE RATINGS					
PARAMETER	SYMBOL	VS-10TQ035SPbF	VS-10TQ045SPbF	UNITS	
Maximum DC reverse voltage	V _R	35	45	V	
Maximum working peak reverse voltage	V _{RWM}	55	45	v	

ABSOLUTE MAXIMUM RAT	NGS				
PARAMETER	SYMBOL	TEST CONDI	TIONS	VALUES	UNITS
Maximum average forward current See fig. 5	I _{F(AV)}	50 % duty cycle at T_C = 151 °C, r	ectangular waveform	10	А
Maximum peak one cycle non-repetitive surge current	1	5 µs sine or 3 µs rect. pulse	Following any rated load condition and with rated	1050	А
See fig. 7	IFSM	10 ms sine or 6 ms rect. pulse	V _{RRM} applied	280	~
Non-repetitive avalanche energy	E _{AS}	T _J = 25 °C, I _{AS} = 2 A, L = 6.5 mH		13	mJ
Repetitive avalanche current	I _{AR}	Current decaying linearly to zero in 1 μ s Frequency limited by T _J maximum V _A = 1.5 x V _R typical		2	А

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ELECTRICAL SPECIFICATIONS

ELECTRICAL SPECIFICATI		l			1
PARAMETER	SYMBOL	TEST	CONDITIONS	VALUES	UNITS
		10 A	T.I = 25 °C	0.57	
Maximum forward voltage drop	V (1)	20 A	1j=25 0	0.67	v
See fig. 1	V _{FM} ⁽¹⁾	10 A	T _{.1} = 125 °C	0.49	
		20 A	1 _J = 125 C	0.61	
Maximum reverse leakage current	I _{RM} ⁽¹⁾	T _J = 25 °C	$V_{\rm B}$ = Rated V _B	2	mA
See fig. 2		T _J = 125 °C	V _R = naleu V _R	15	
Maximum junction capacitance	CT	$V_{R} = 5 V_{DC}$ (test signal	range 100 kHz to 1 MHz), 25 °C	900	pF
Typical series inductance	L _S	Measured lead to lead	d 5 mm from package body	8.0	nH
Maximum voltage rate of change	dV/dt	Rated V _R		10 000	V/µs

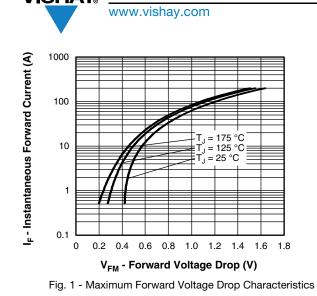
Note

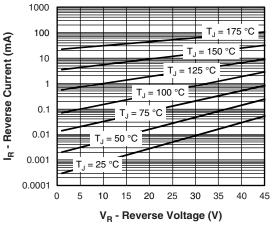
 $^{(1)}\,$ Pulse width < 300 $\mu s,$ duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER		SYMBOL TEST CONDITIONS		VALUES	UNITS	
Maximum junction and sto temperature range	orage	T _J , T _{Stg}		-55 to +175	°C	
Maximum thermal resistar junction to case	nce,	R _{thJC}	DC operation See fig. 4	. 2.0		
Typical thermal resistance case to heatsink	9,	R _{thCS}	Mounting surface, smooth and greased	0.50	°C/W	
Approvimate weight				2	g	
Approximate weight				0.07	oz.	
	minimum			6 (5)	kgf · cm	
Mounting torque	maximum			12 (10)	(lbf \cdot in)	
Marking device			Case style D ² PAK	10TQ	045S	

VS-10TQ035SPbF, VS-10TQ045SPbF









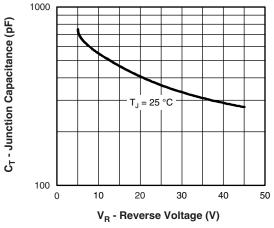


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

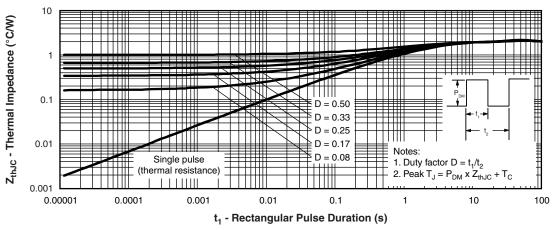
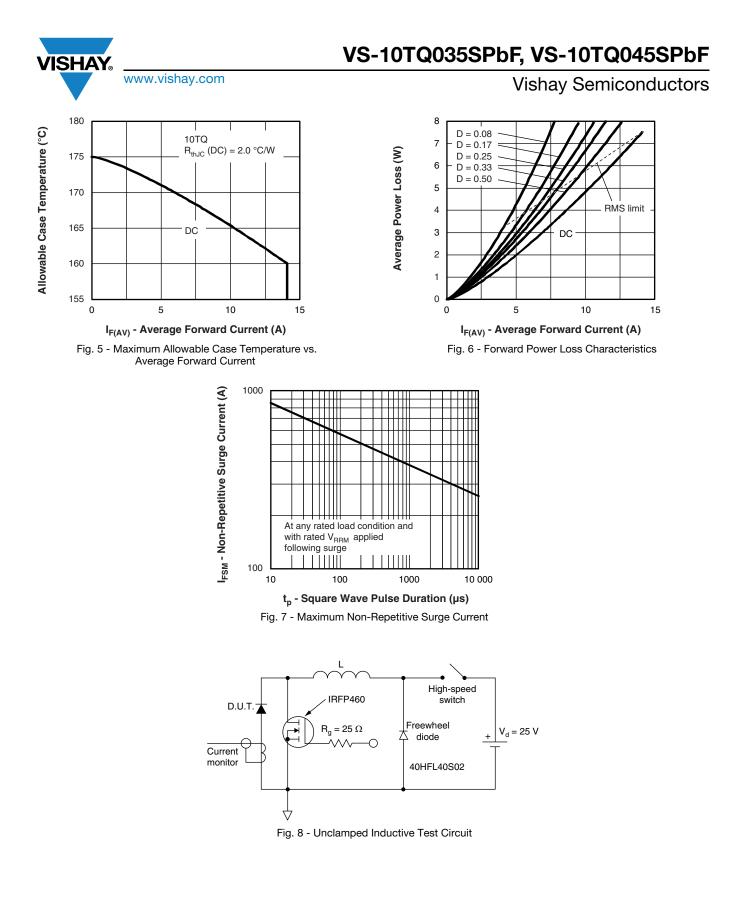


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics

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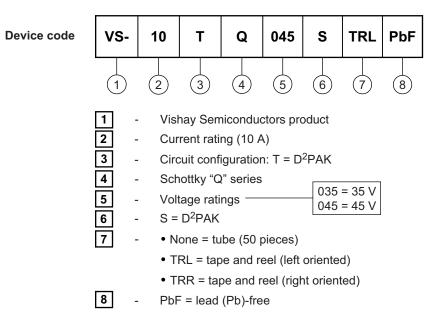




VS-10TQ035SPbF, VS-10TQ045SPbF

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ORDERING INFORMATION TABLE



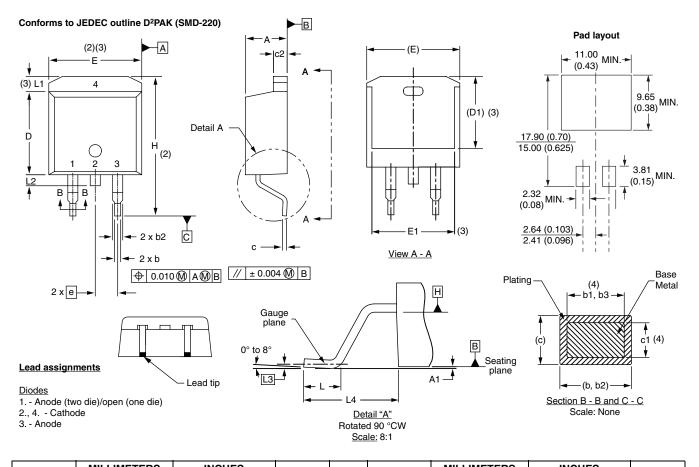
LINKS TO RELATED DOCUMENTS			
Dimensions	www.vishay.com/doc?95014		
Part marking information	www.vishay.com/doc?95008		
Packaging information	www.vishay.com/doc?95032		

Vishay High Power Products

D²PAK, TO-262

DIMENSIONS FOR D²PAK in millimeters and inches

SHA



SYMBOL	MILLIMETERS		INCHES		NOTES
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
A	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
с	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIM	ETERS	INC	HES	NOTES
	MIN.	MAX.	MIN.	MAX.	NOTES
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54 BSC		0.100	BSC	
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L2	1.27	1.78	0.050	0.070	
L3	0.25	BSC	0.010	BSC	
L4	4.78	5.28	0.188	0.208	

⁽⁷⁾ Outline conforms to JEDEC outline TO-263AB

Notes

- ⁽¹⁾ Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- $^{(3)}\,$ Thermal pad contour optional within dimension E, L1, D1 and E1
- ⁽⁴⁾ Dimension b1 and c1 apply to base metal only
- ⁽⁵⁾ Datum A and B to be determined at datum plane H
- ⁽⁶⁾ Controlling dimension: inch

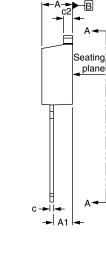
Vishay High Power Products

D²PAK, TO-262



DIMENSIONS FOR TO-262 in millimeters and inches







Lead tip



SYMBOL	MILLIMETERS		INCH	INCHES		
	MIN.	MAX.	MIN.	MAX.	NOTES	
А	4.06	4.83	0.160	0.190		
A1	2.03	3.02	0.080	0.119		
b	0.51	0.99	0.020	0.039		
b1	0.51	0.89	0.020	0.035	4	
b2	1.14	1.78	0.045	0.070		
b3	1.14	1.73	0.045	0.068	4	
С	0.38	0.74	0.015	0.029		
c1	0.38	0.58	0.015	0.023	4	
c2	1.14	1.65	0.045	0.065		
D	8.51	9.65	0.335	0.380	2	
D1	6.86	8.00	0.270	0.315	3	
E	9.65	10.67	0.380	0.420	2, 3	
E1	7.90	8.80	0.311	0.346	3	
е	2.54 BSC		0.100	BSC		
L	13.46	14.10	0.530	0.555		
L1	-	1.65	-	0.065	3	
L2	3.56	3.71	0.140	0.146		

Notes

- ⁽¹⁾ Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- ⁽³⁾ Thermal pad contour optional within dimension E, L1, D1 and E1

⁽⁴⁾ Dimension b1 and c1 apply to base metal only

⁽⁵⁾ Controlling dimension: inches

⁽⁶⁾ Outline conform to JEDEC TO-262 except A1 (maximum), b (minimum) and D1 (minimum) where dimensions derived the actual package outline

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